S8 (E) Package Outline Drawing

NOTES:
1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
   △ DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
   △ DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
5. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

Package Information

<table>
<thead>
<tr>
<th>Part Number Suffix</th>
<th>Package Body Material</th>
<th>Lead Finish</th>
<th>MSL Rating</th>
<th>Package Marking</th>
</tr>
</thead>
<tbody>
<tr>
<td>S8</td>
<td>RoHS Compliant Mold Compound</td>
<td>Sn/Pb Solder</td>
<td>MSL1 [1]</td>
<td>HMCNNN XXXX</td>
</tr>
<tr>
<td>S8E</td>
<td>RoHS Compliant Mold Compound</td>
<td>100% matte Sn</td>
<td>MSL1 [2]</td>
<td>HMCNNN XXXX</td>
</tr>
</tbody>
</table>

[1] Max peak reflow temperature of 235 °C
[3] 4-Digit lot number XXXX
[4] 3-Digit part number NNN
Suggested S8 (E) PCB Land Pattern

NOTES:
1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.